1. Record Nr. UNINA9910461281303321 Autore Robertson Max Titolo Substrate Surface Preparation Handbook Pubbl/distr/stampa Norwood:,: Artech House,, 2011 [Piscatagay, New Jersey]:,: IEEE Xplore,, [2011] **ISBN** 1-5231-1759-1 1-60807-214-2 Descrizione fisica 1 online resource (196 p.) Collana Artech House applied photonics series Disciplina 621.3815 671 Soggetti Optical materials - Surfaces Glass grinding and polishing Electronic books. Lingua di pubblicazione Inglese **Formato** Materiale a stampa Livello bibliografico Monografia Note generali Description based upon print version of record. Nota di bibliografia Includes bibliographical references and index. Nota di contenuto Substrate SurfacePreparation Handbook; Contents; Foreword; Preface; 1 Introduction; 1.1 Choosing a Process; 1.2 Definitions of Processes Used in This Book; 1.3 Lapping, Grinding, and Polishing Abrasives; 2 Preparation: Before the Start; 2.1 Plates and Measurement; 2.1.1 Plate Measurement; 2.1.2 Maintaining Plate Shape; 2.2 Lapping Plates; 2.2.1 Glazing; 2.3 Polishing Plates; 2.4 Polishing Surfaces: Care and Conditioning: 2.5 Baseplates for Polishing: 2.5.1 Baseplate Materials: 2.6 The Use of Smoothing Blocks; 2.7 Jigs; 2.7.1 When to Use a Jig; 2.7.2 Jig Balance; 2.7.3 Jig Maintenance. 2.8 Sample Mounting2.8.1 Vacuum Mounting; 2.8.2 Wax Mounting; 2.8 -- Automated Bonding; 2.8.4 Evaporated Wax Films; 2.8.5 Surface Tension Mounting; 2.8.6 Epoxy Bonding; 2.9 Sample Viewing and Assessment; 2.10 Plate and Sample Flatness Control; 2.10.1 Wafer Distortion; 2.11 Conclusion; References; 3 Lapping; 3.1 The Lapping Process; 3.1.1 If the Stock Removal Is Too Slow; 3.1.2 If the Stock Removal Is Too Fast: 3.2 Plate Shape Monitoring: 3.3 Scratching: 3.4 Smoothing; References; 4 Polishing; 4.1 Introduction; 4.2 Sample Load; 4.3 Abrasives; 4.4 Edge Polishing; 4.5 Slurry Flow Rate.

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## Sommario/riassunto

Substrate Surface Preparation serves as a practical, one-stop reference, covering the technologies developed to produce flat surfaces with nanometer accuracy for the subsequent building of semiconductor devices and integrated circuits. This hands-on resource offers you detailed guidance in the entire substrate surface preparation process, from lapping and polishing ... to specialized techniques and surface finishing. Supported with over 125 illustrations, this unique book provides you with a complete understanding of important maintenance methods and the full range of equipment available in the fi.

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